

State of the art in Microfabrication

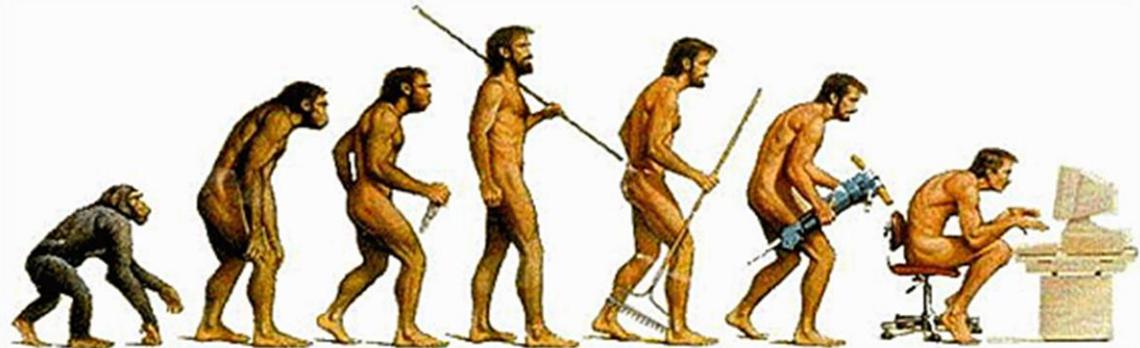
Jurriaan Schmitz

j.schmitz@utwente.nl -- www.utwente.nl/ewi/sc



Contents

- Microelectronics: Moore's Law today
- Technology advances inside the microchip
- Other microfabricated devices
- Prospects for radiation imaging



The beginning: 1960s

1958 Fairchild

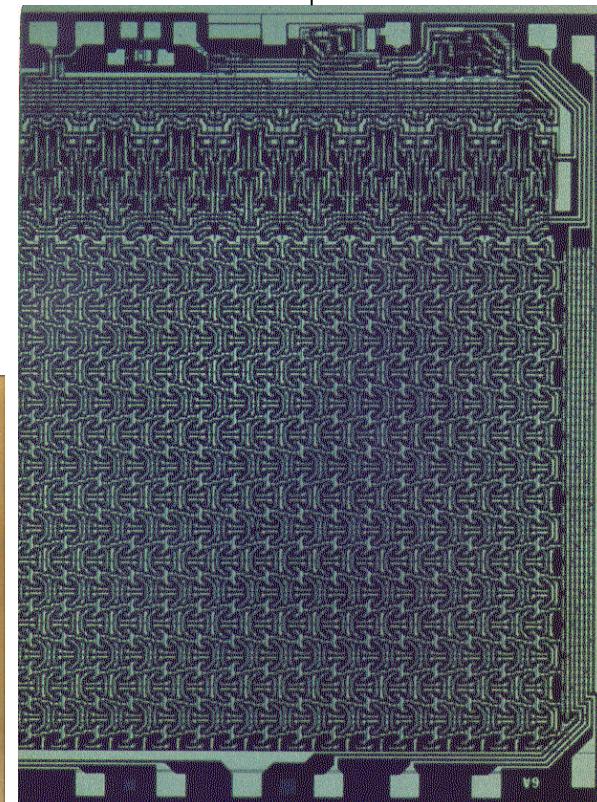
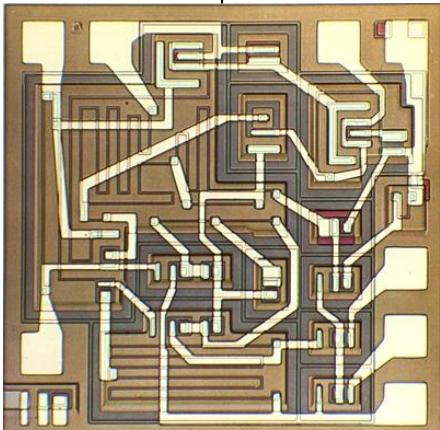
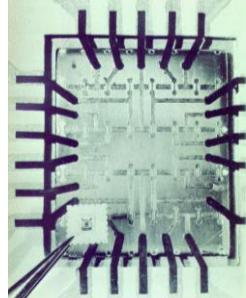
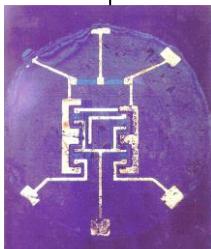
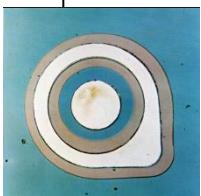
First planar transistor

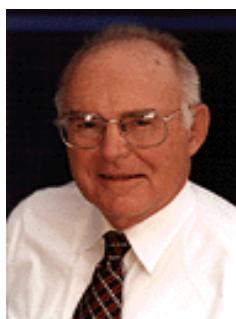
1965 Fairchild
opamp

1968 Fairchild
2kT SRAM chip

1962 RCA
16T logic chip

1961 Fairchild
4T5R flip-flop





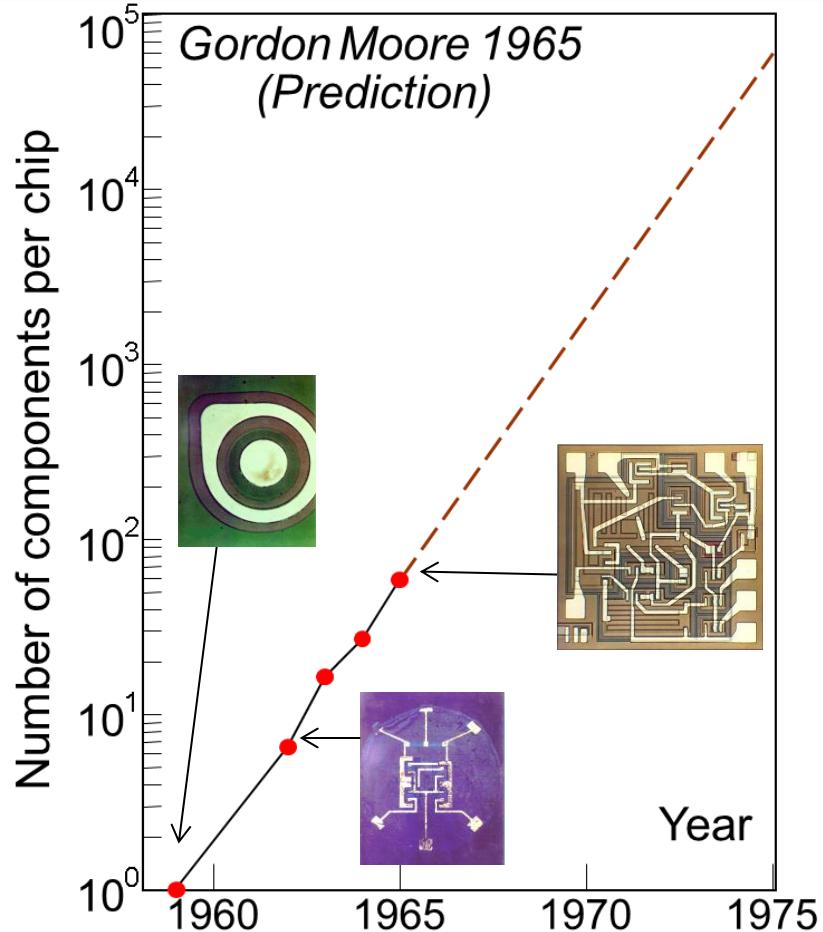
Gordon Moore 1965

Transistors keep getting cheaper!

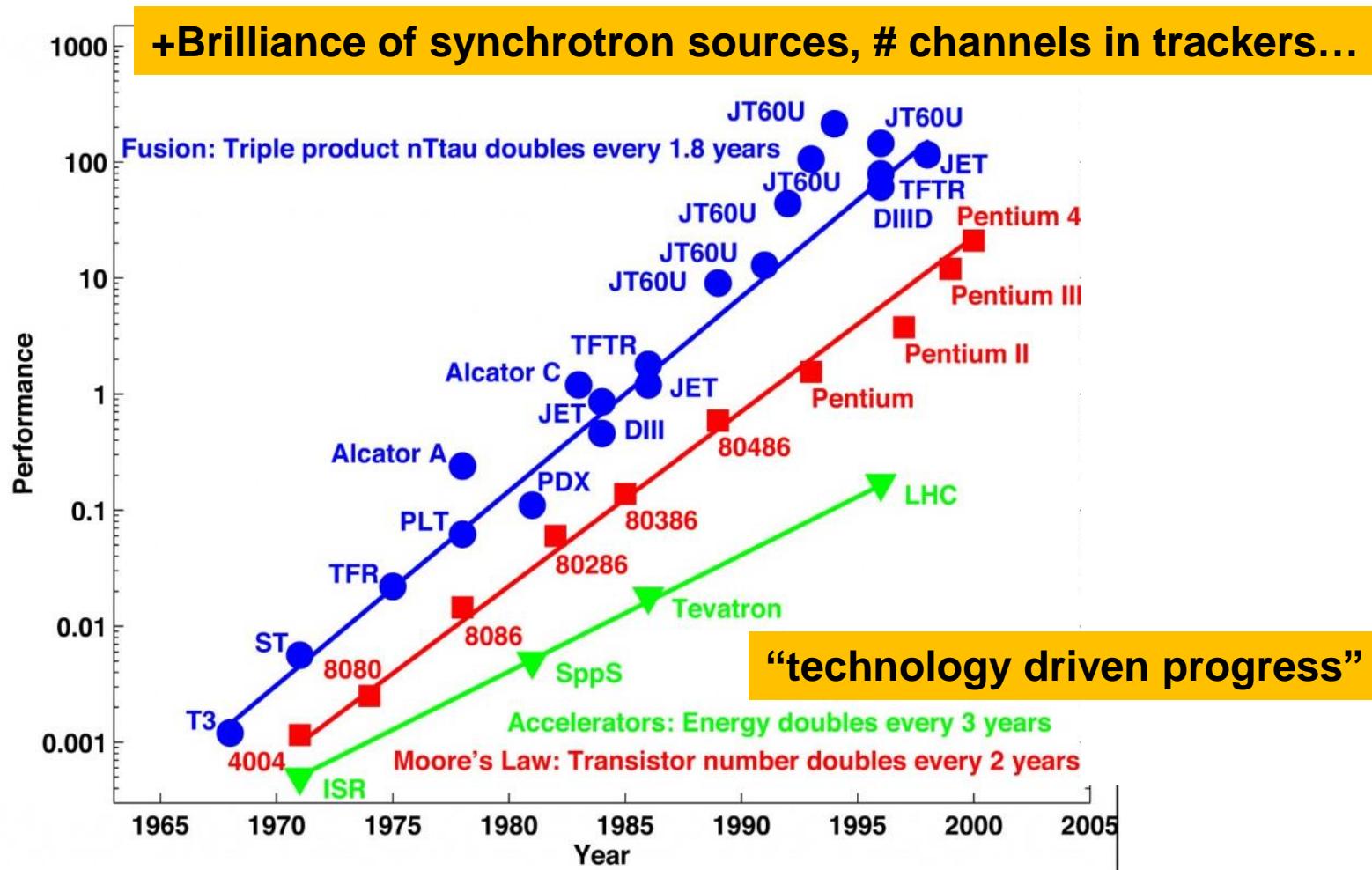
- Smaller components
- Bigger chips & wafers
- Better skills

“Moore’s Law”:

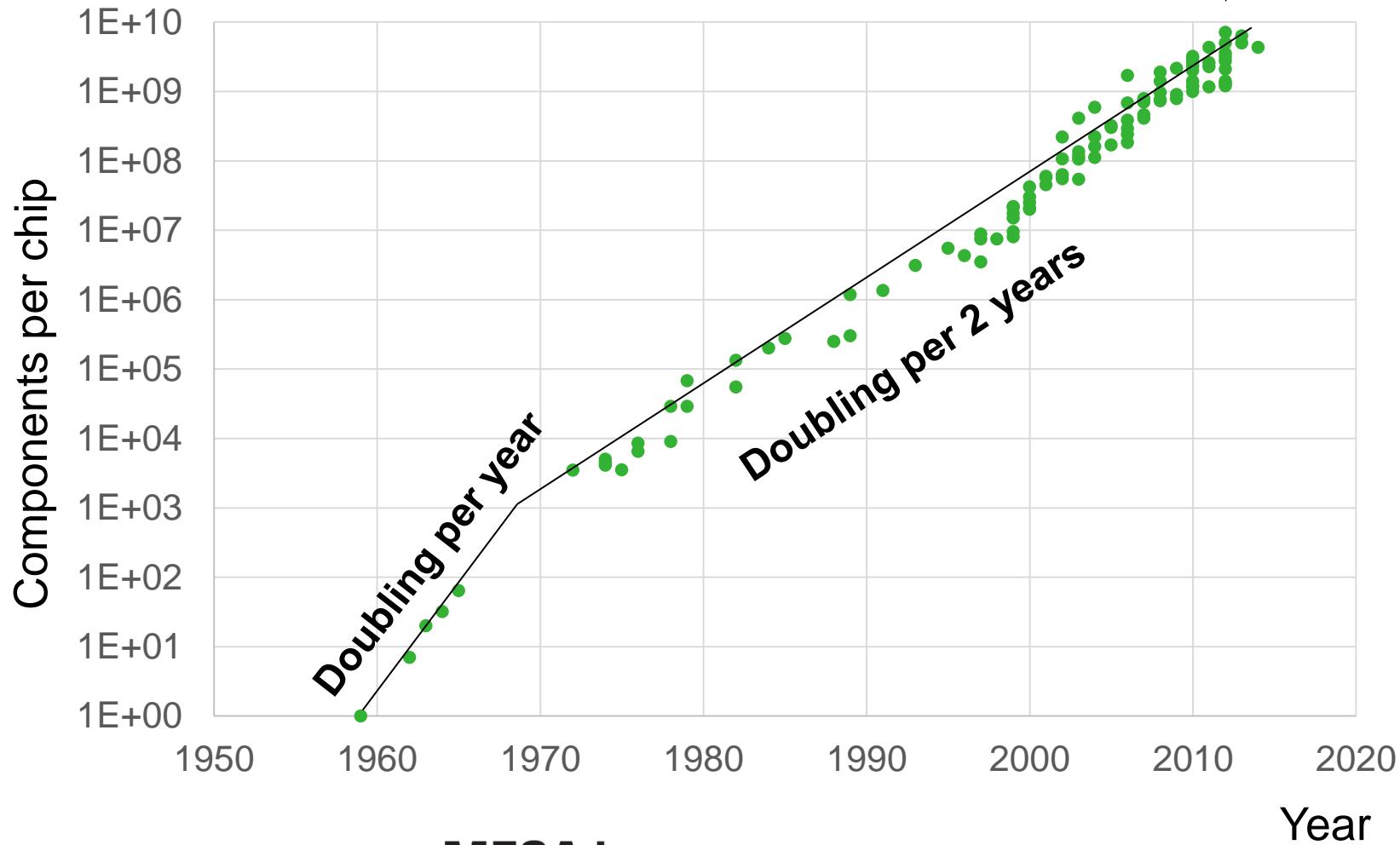
The number of components on a chip doubles every year

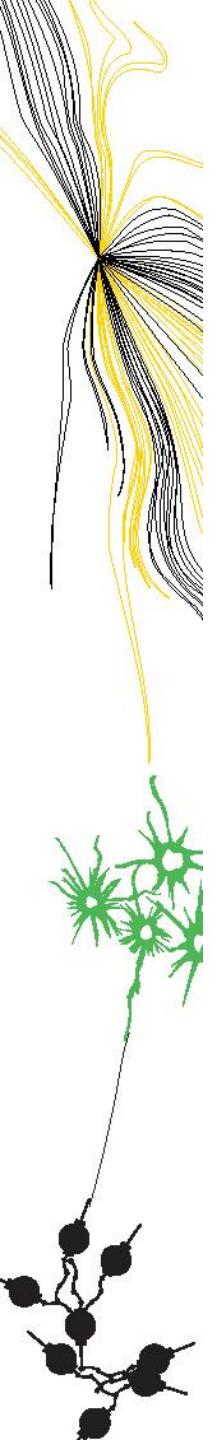


Moore's Law – chips, accelerators, fusion...



How is Moore's Law keeping up?





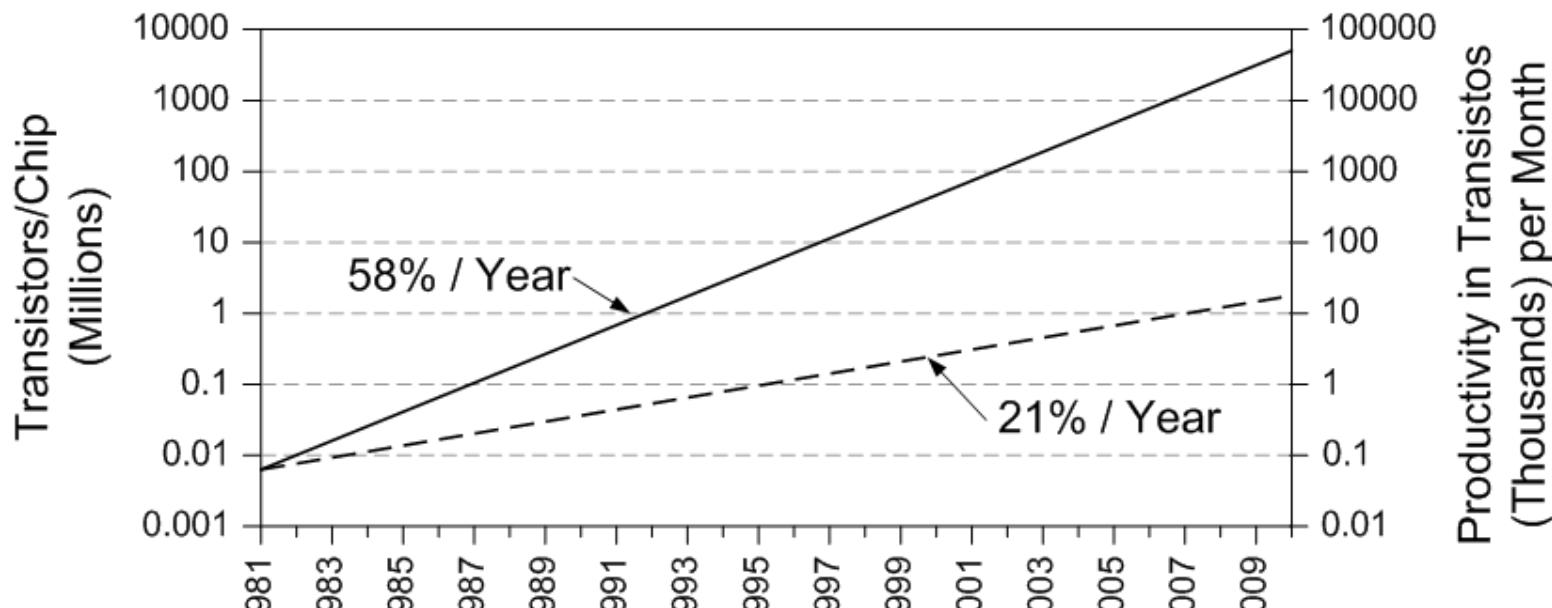
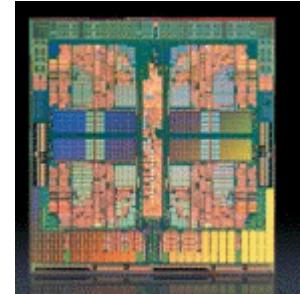
Moore's Law: perspective

- Transistor gate length scaling is slowing down (10% per generation)
- 300 → 450 mm transition is delayed to 2020
- ITRS roadmap: multiple breakthroughs required by 2018
- ... what happens next?



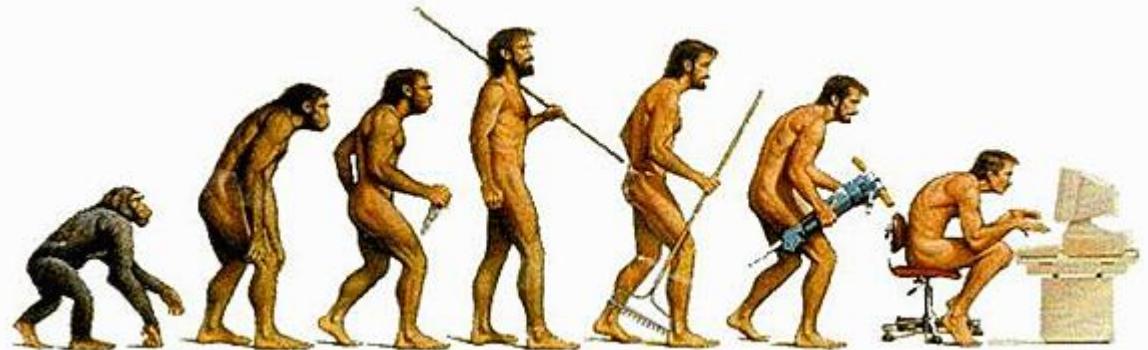
Microchips keep getting better

- Design gap
- Multicore processors
- Transistor performance boosters



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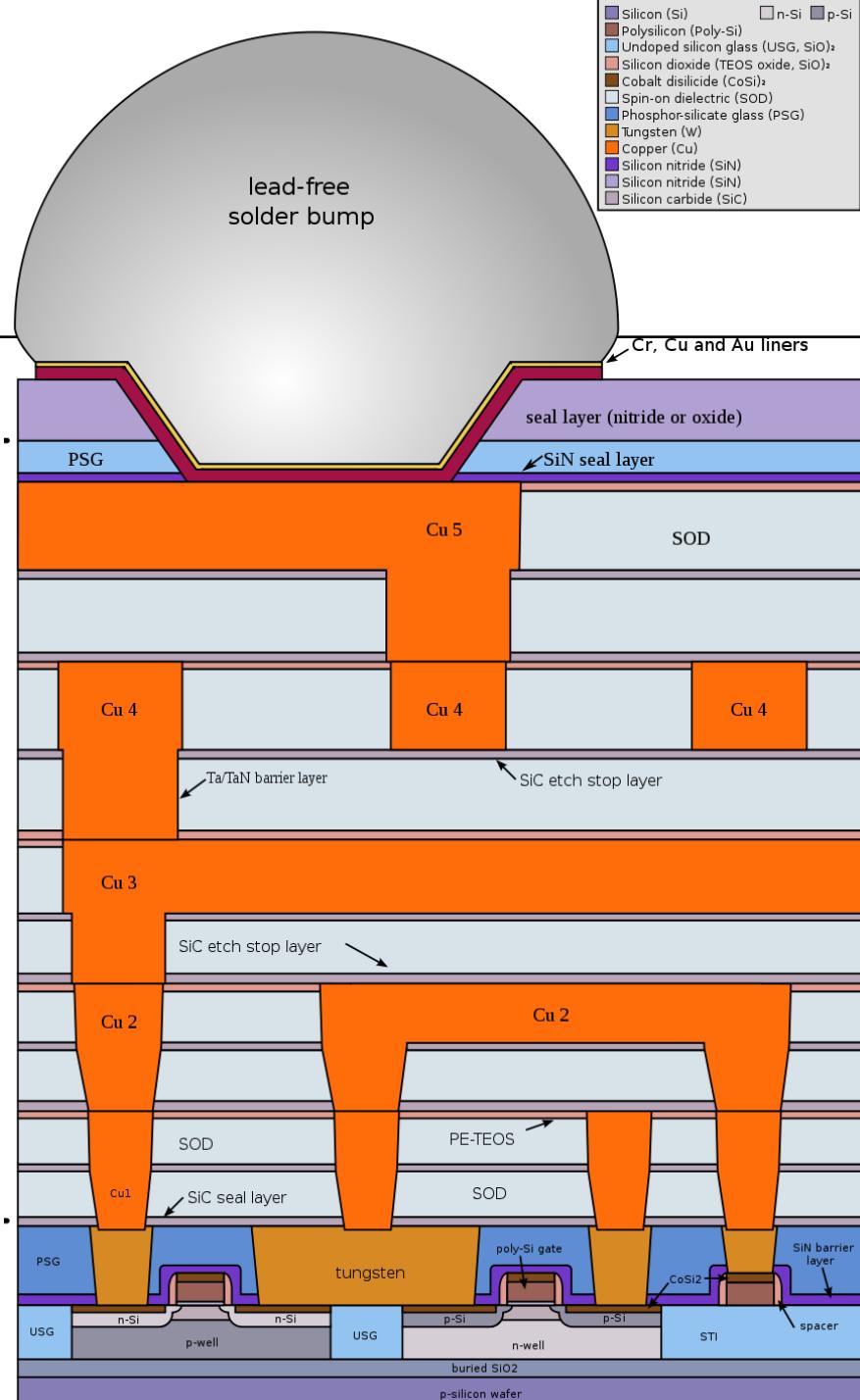
The CMOS chip

Complexity is more than transistors alone:

A cm² chip may contain
~20 km wires
~10¹⁰ contacts

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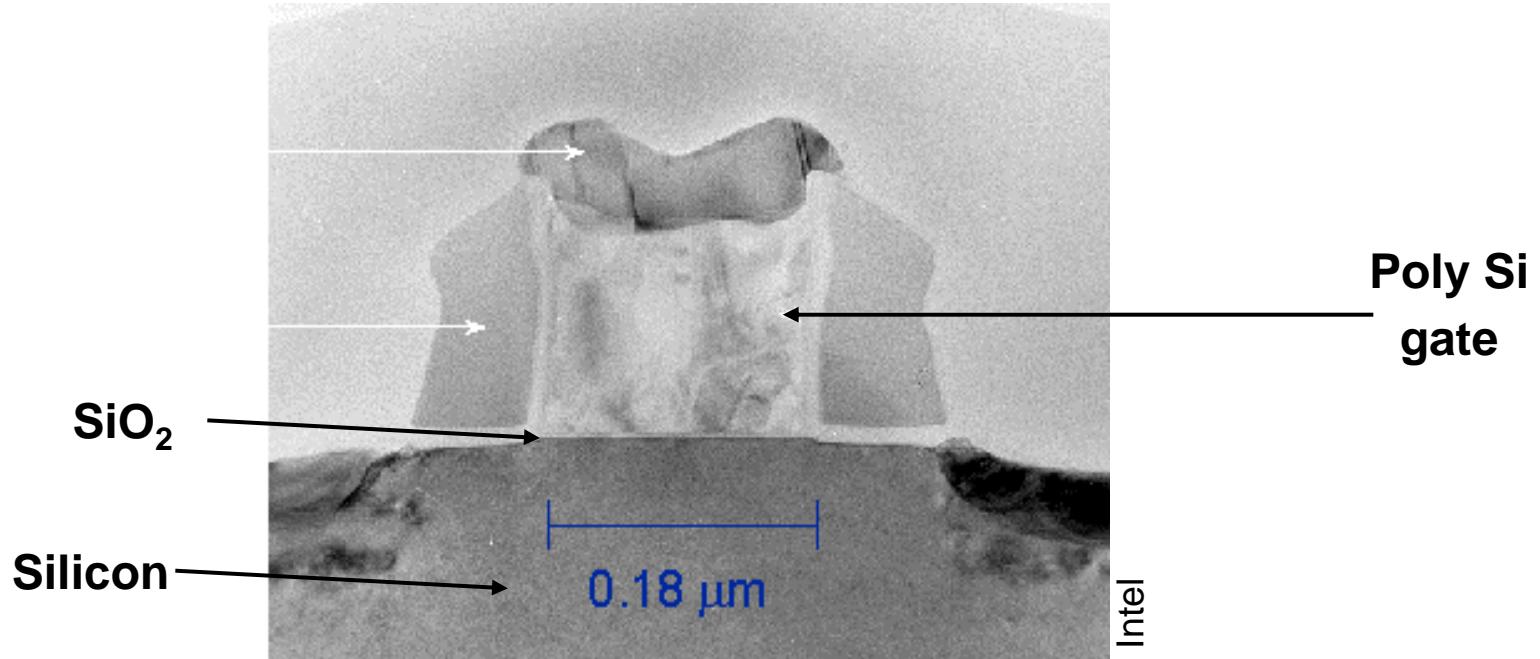
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Transistor evolution

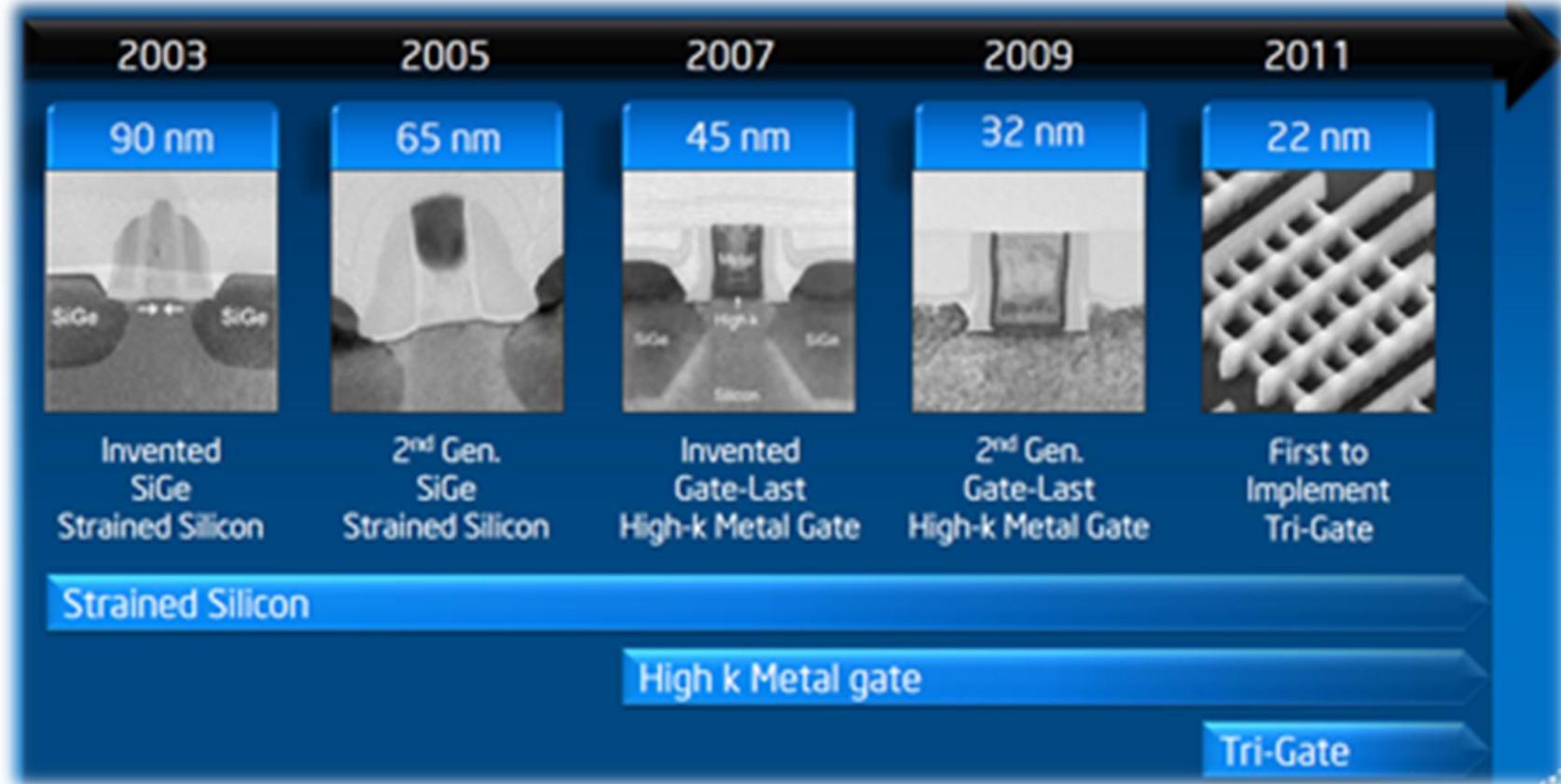
1970-2000: “the happy scaling era”

- Keep everything the same, only miniaturize it: $1/\sqrt{2}$ per generation



Transistor evolution (2)

2000-present: new technologies to boost performance



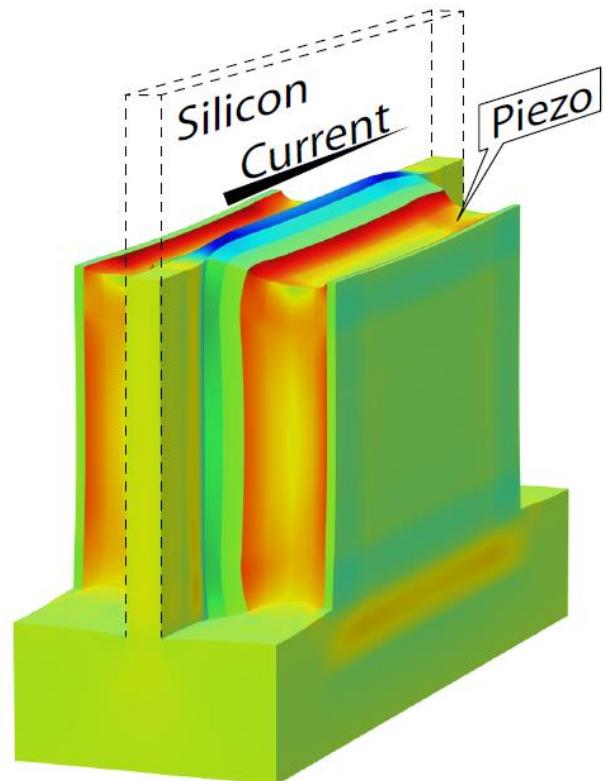
Intel

Another performance booster: Permanent strain → active strain modulation

- Switch strain on and off
- Use piezoelectric material (e.g. PZT)
- High on-current & low off-current

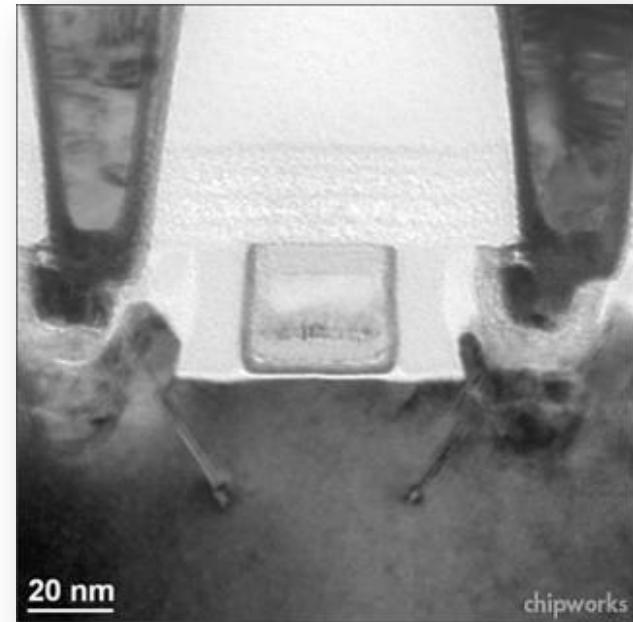
T. Van Hemert et al., IEEE Trans. El. Dev. 2013

B. Kaleli et al., IEEE Trans. El. Dev. 2014



The art of microchips today

- 1-nm precision manufacturing
- Atomary sharp interfaces
- High-purity materials
- Best mastered:
 - Aluminum, copper, tungsten
 - Silicon; SiGe alloys
 - SiO_2 , HfO_2 , Si_3N_4

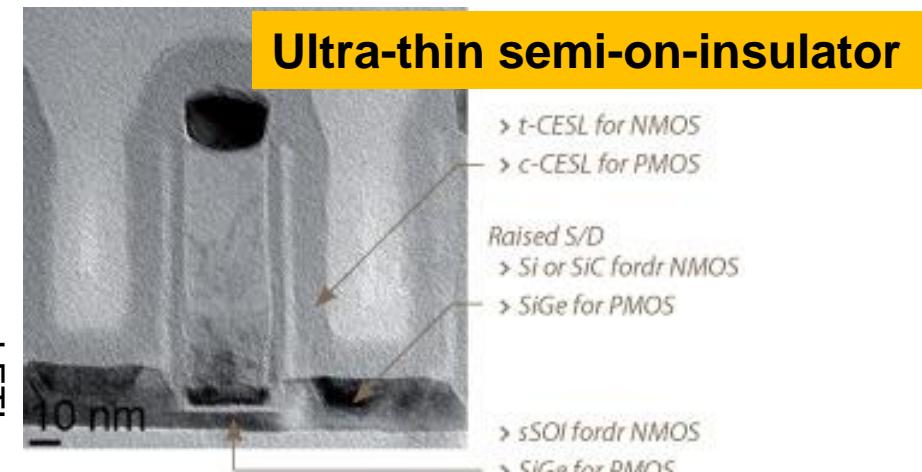
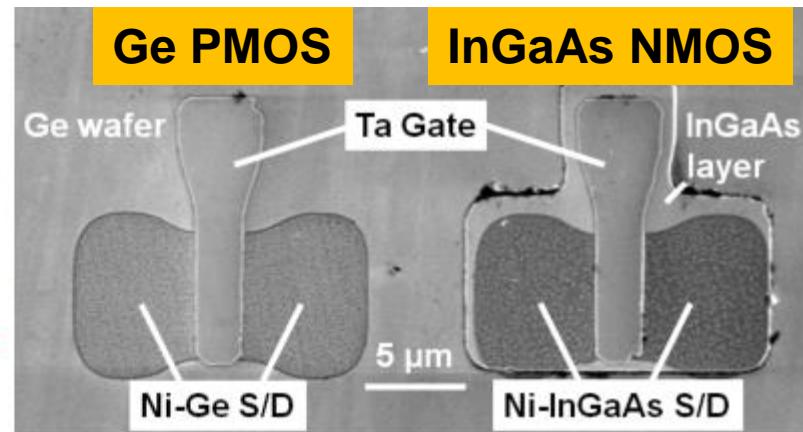
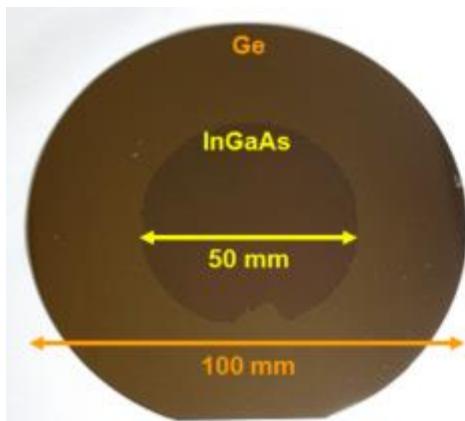


Conventional wisdom:

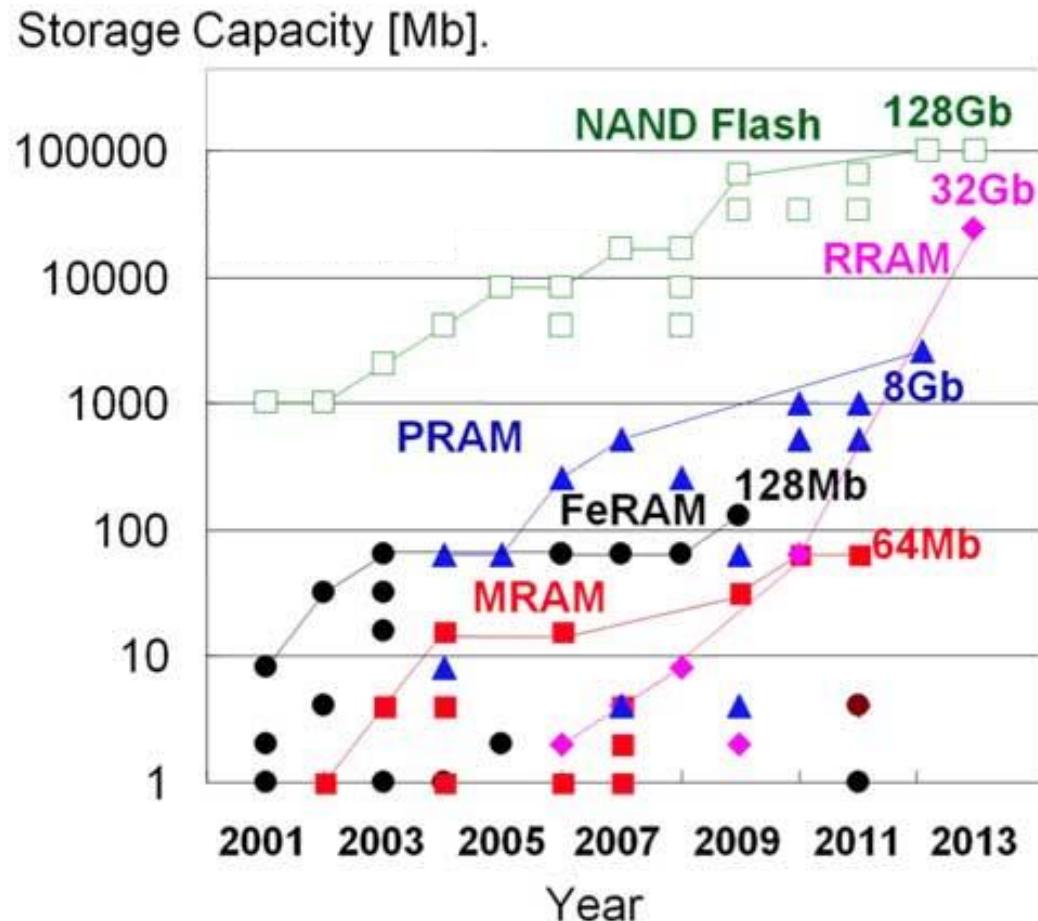
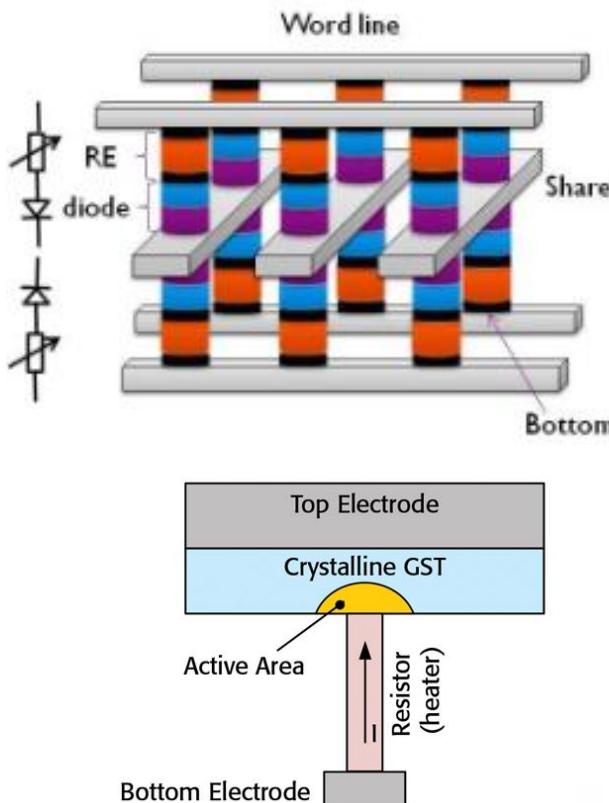
“If you can do it in CMOS, do it in CMOS”

“If you can do it in silicon, do it in silicon”

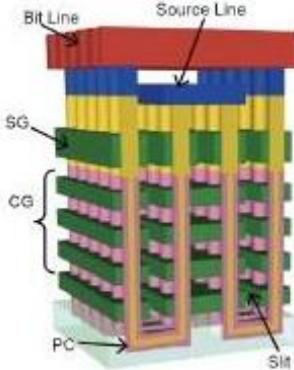
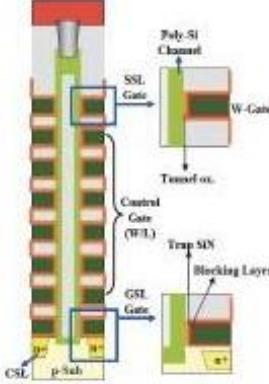
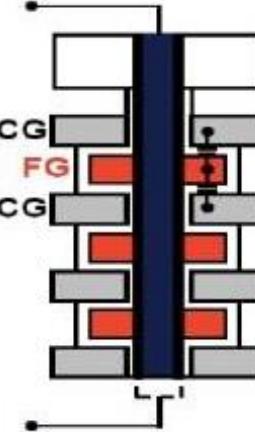
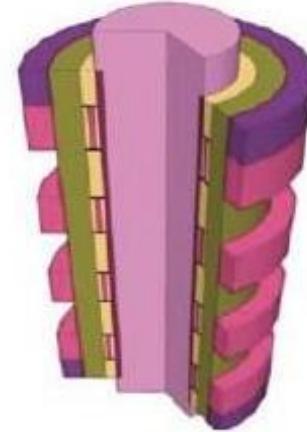
Emerging technologies in microelectronics: Replacing good old silicon



Emerging technologies in microelectronics: Replacing FLASH memory

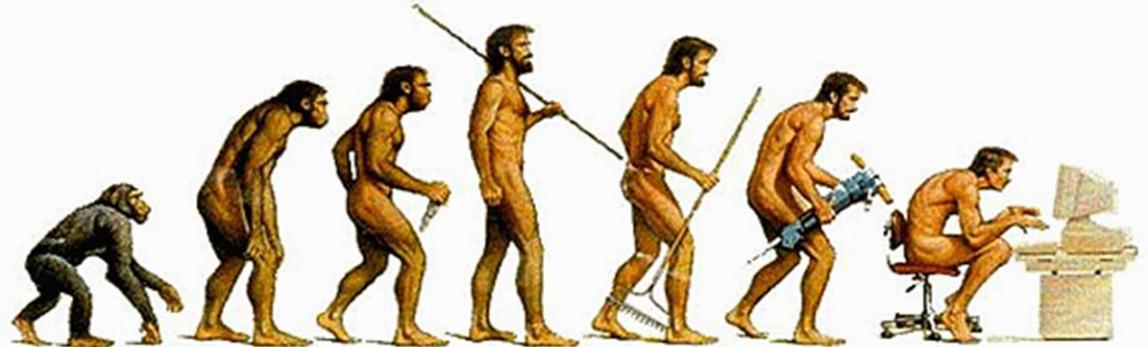


But meanwhile, FLASH is going 3D

	p-BiCS (Toshiba)	TCAT (Samsung)	3D FG (Hynix)	Micron
Structure	 Tanaka. H, VLSIT 2007	 J. Jang, VLSIT 2009	 S. Whang, IEDM 2010	 G. Hawk, FMS 2011
Key Features	- P+ SONOS Cell	- TANOS Cell	- Floating Gate	?

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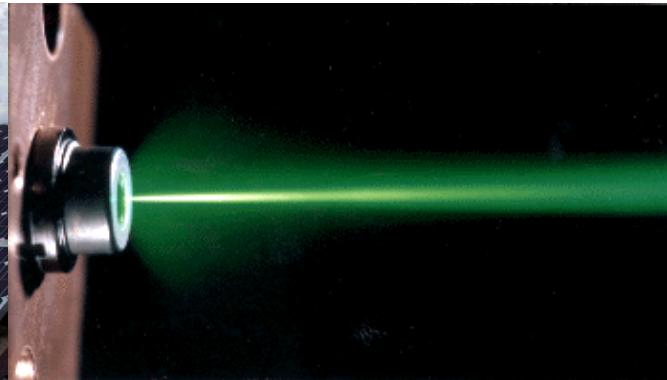
Microtechnology: more than chips



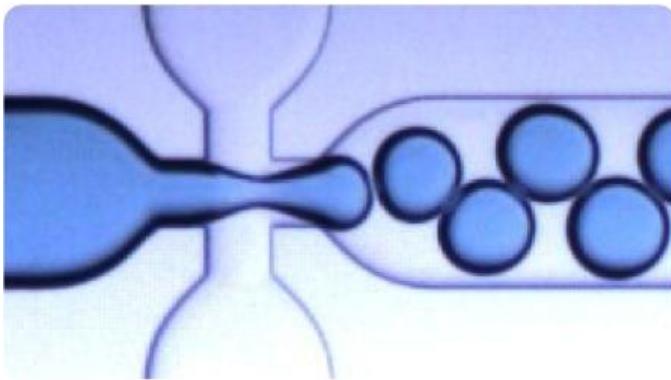
Light Emitting Diodes



Photovoltaics



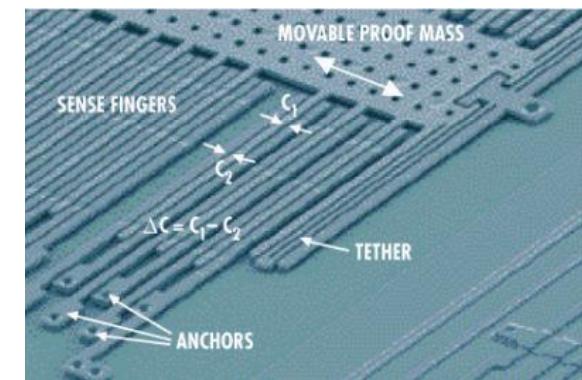
Semiconductor lasers



Microfluidics



Flat Panel Displays

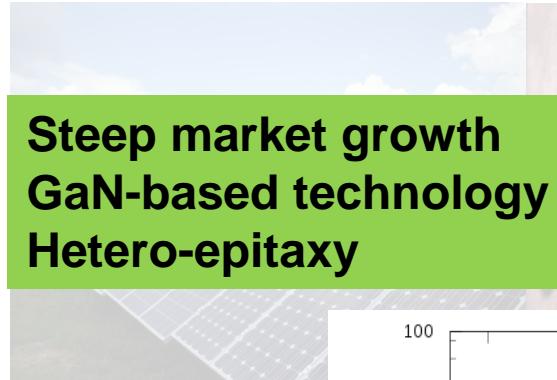


Sensors

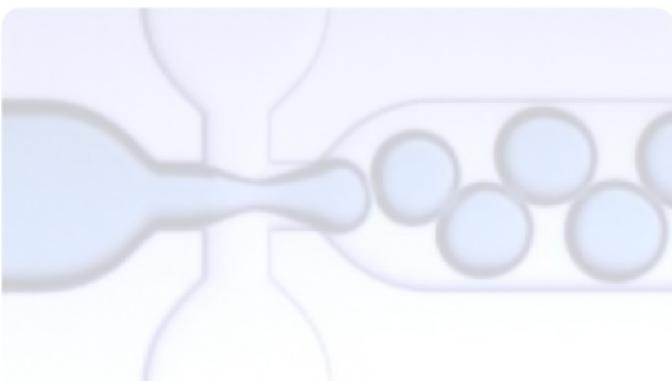
Microtechnology: more than chips



Light Emitting Diodes



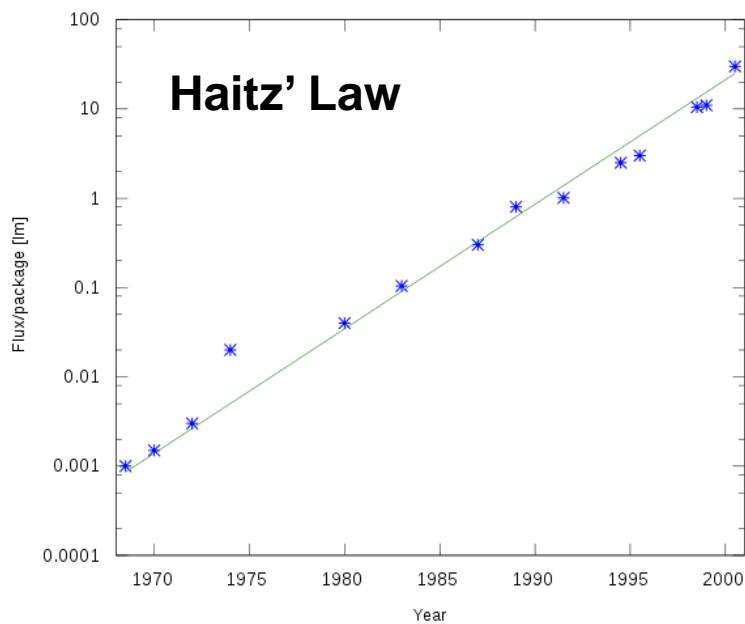
Photovoltaic



Microfluidics



Flat Panel



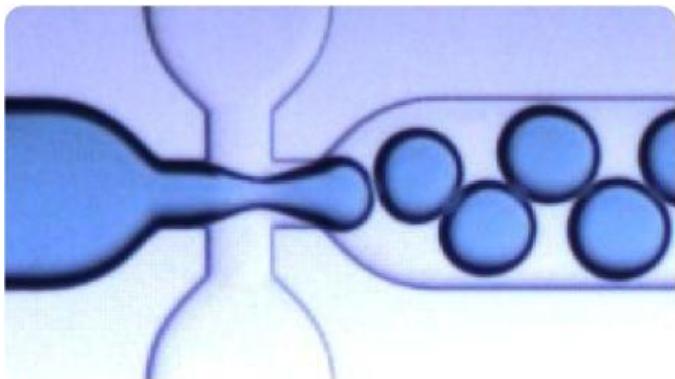
Microtechnology: more than chips



Light Emitting Diodes



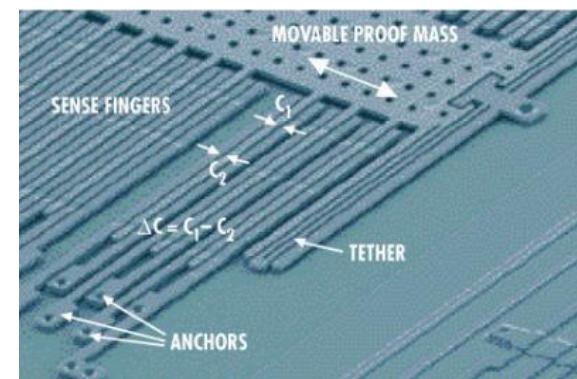
**High potential:
Point-of-care medicine
Internet-of-things
Uses mainstream technology**



Microfluidics



Flat Panel Displays



Sensors

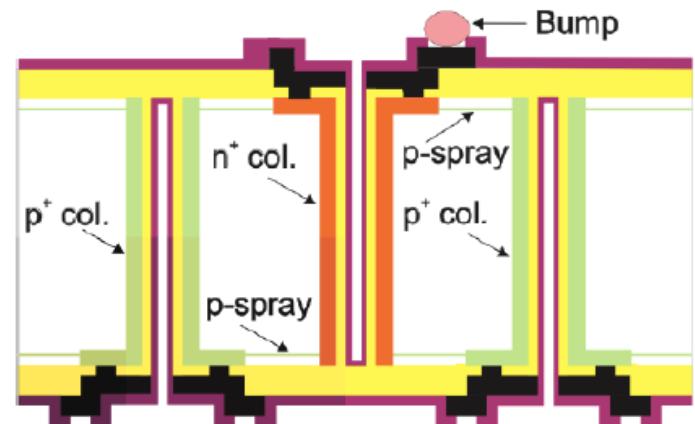
...and sensors for radiation imaging!

Microfabricated sensors in particle physics:

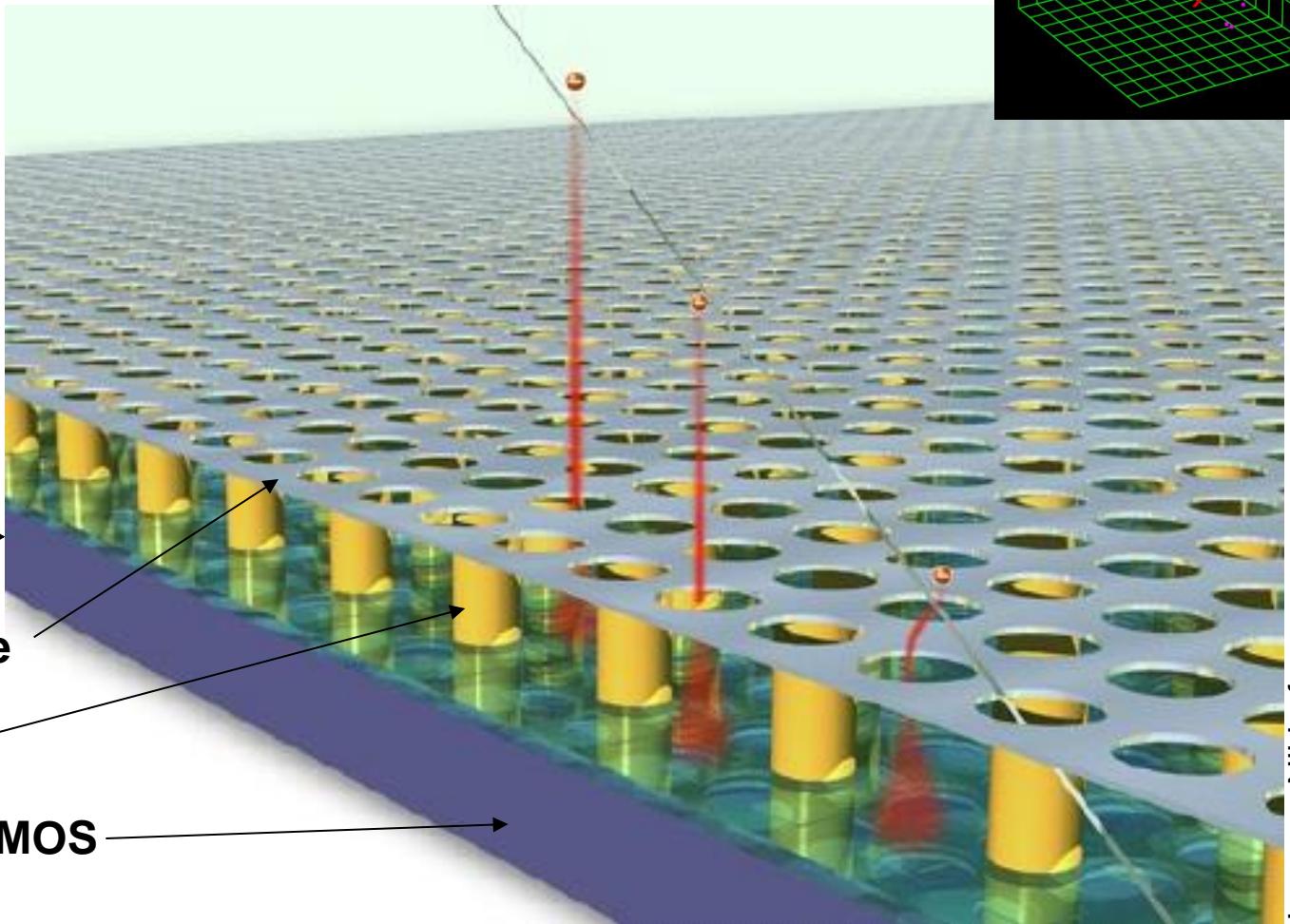
- Silicon detectors
- Charge-coupled devices
- Silicon photomultipliers
- CMOS-APS based detectors
- ...

Focus on semiconductors for signal generation.

- Scintillators? Gas?

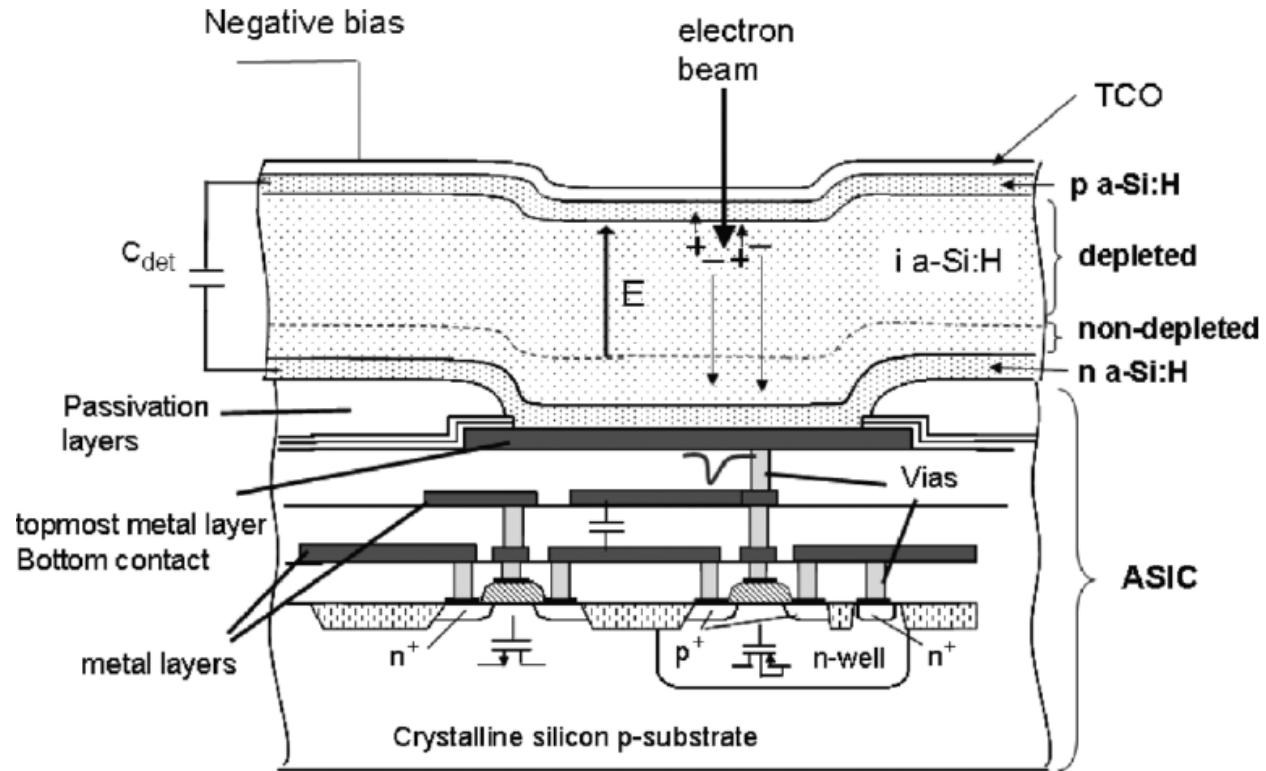


InGrid: a radiation imaging detector



Images: Nikhef

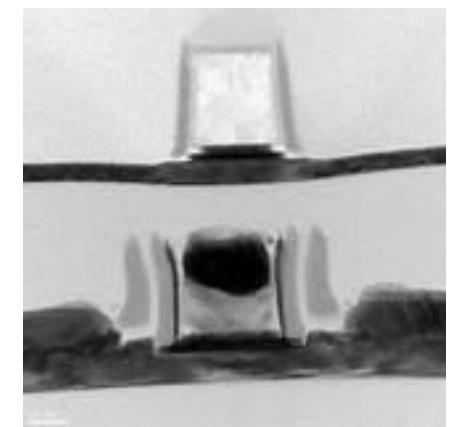
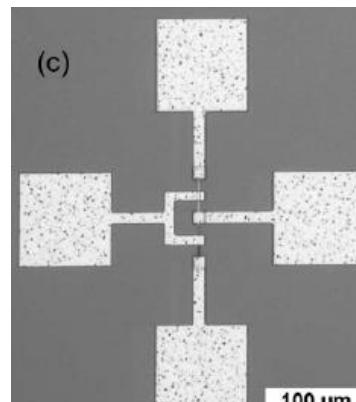
Semiconductors on top of CMOS



"TFA detector", Andrea Franco et al., IEEE Trans. Nucl. Sci. 2012

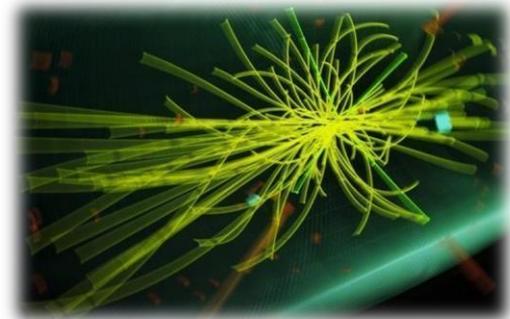
Or vice versa?

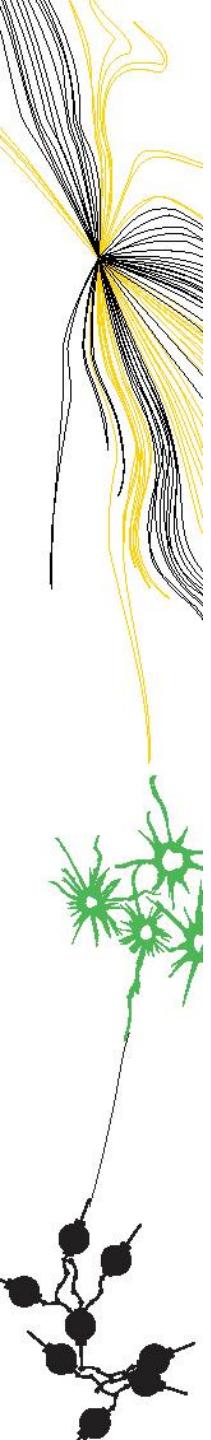
- Stack thin-film transistors on your sensor
- Monocrystalline: 3D electronics as developed e.g. by LETI (Bature et al.)
- Polycrystalline:
e.g. I. Brunets et al.,
IEEE Trans. El. Dev. 2009
- Low temp fabrication (~400 °C)
- High interconnect density >> TSV's



Advances in microfabrication: Consequences for Particle Physics

- Miniaturized detector systems may boast
 - Improved resolution and speed
 - Reduced power consumption
 - Less X_0 , lower mass
 - Onboard intelligence
 - “The interconnect benefit”
- IC Future: new materials & lower-power circuits
 - New semiconductor materials: GaN, InGaAs, Ge, ...
 - Performance in radiation imaging?



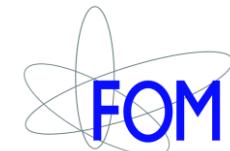


Thank you:

- My coworkers at the University of Twente
- Nikhef Detector R&D group
- TIPP organizers
- Dutch Technology Foundation STW, Min. Economic Affairs, FOM and EU



Ministerie van Economische Zaken



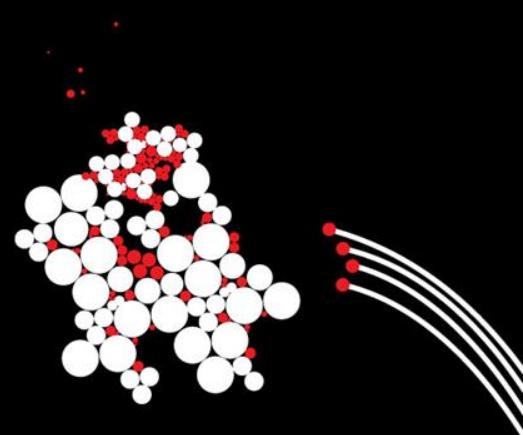
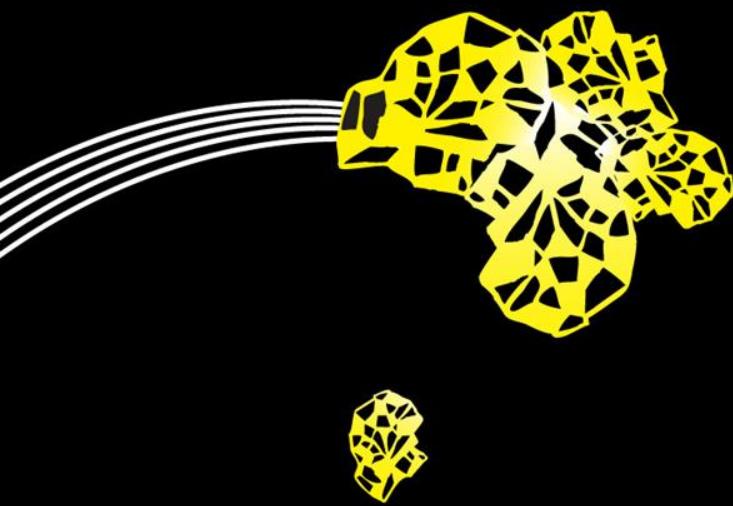
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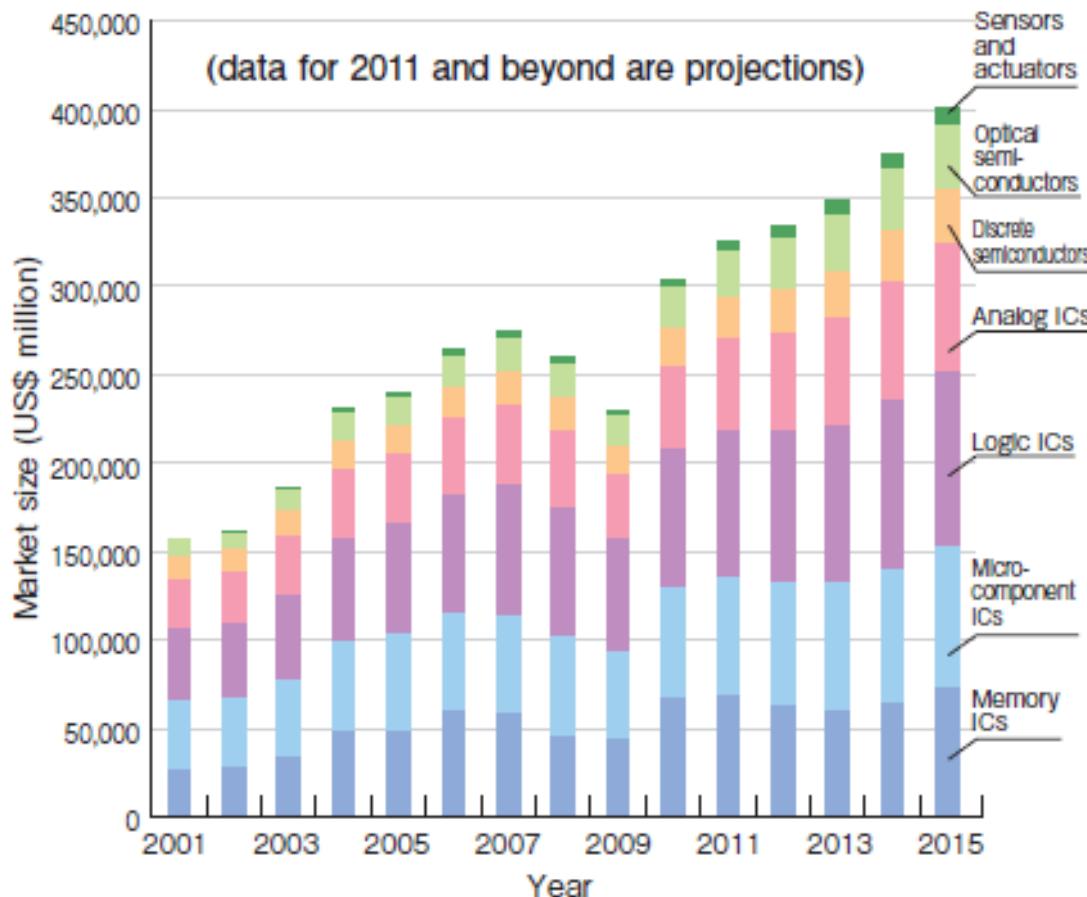
TIPP 2014, Amsterdam

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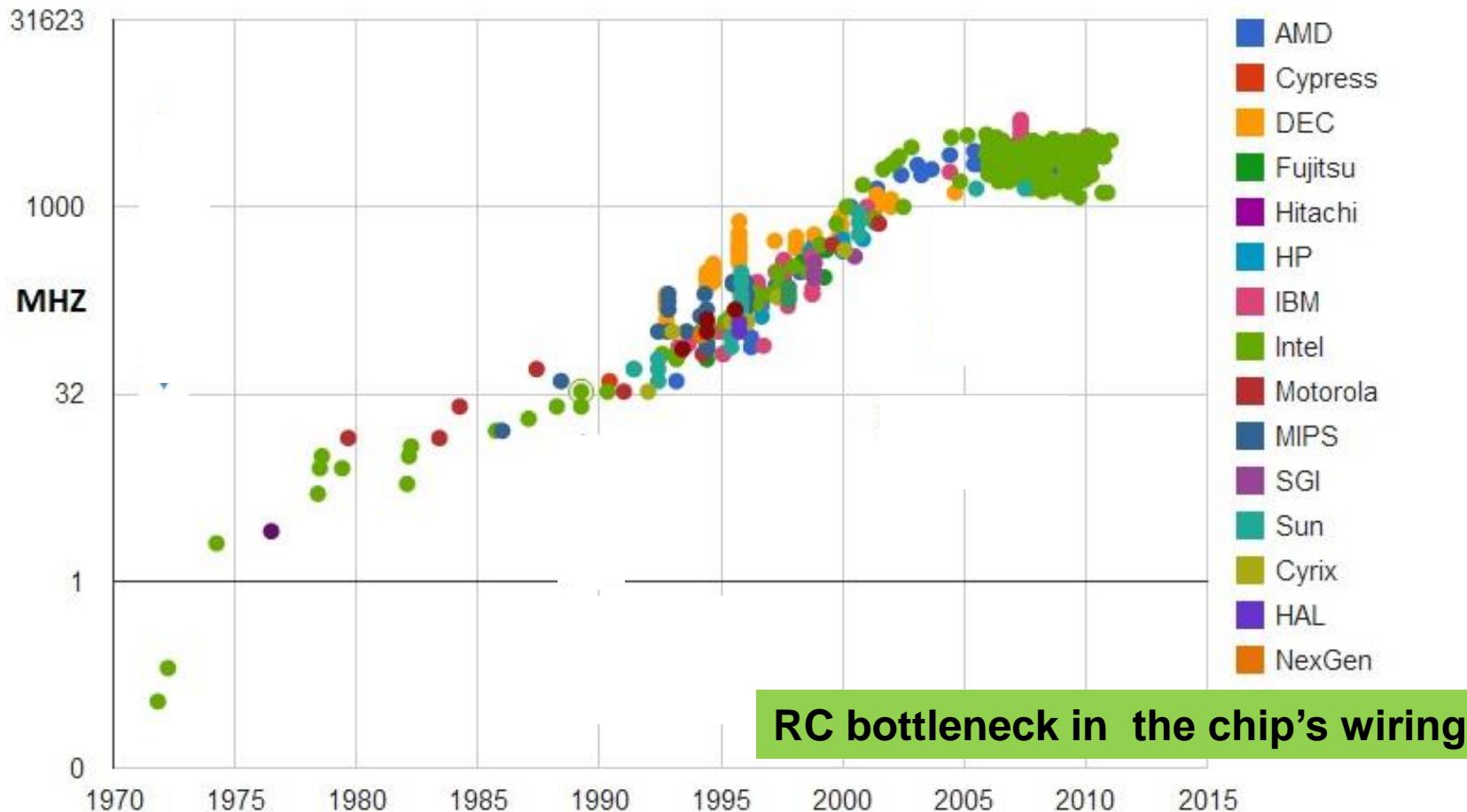
Questions?



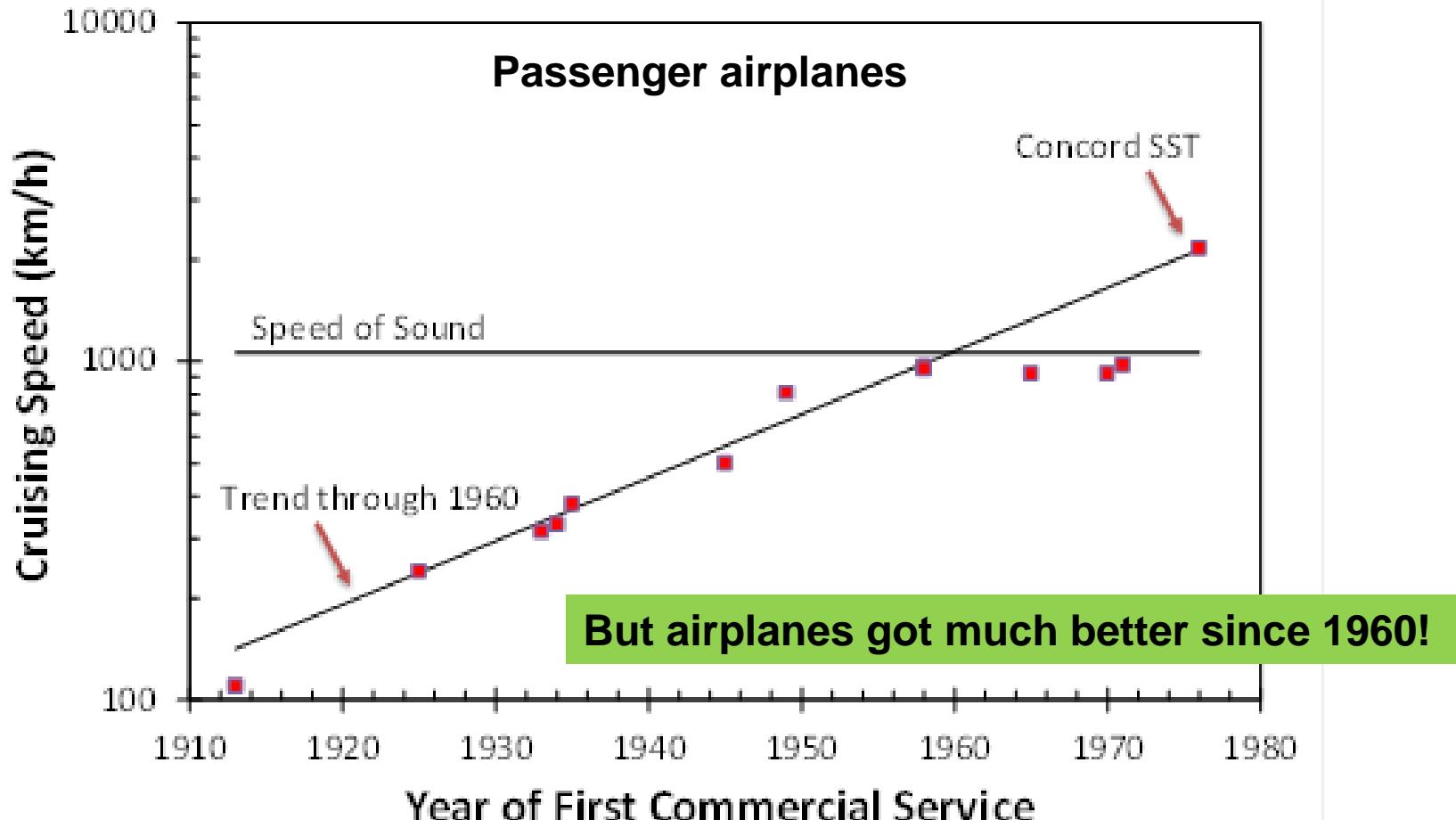
Semiconductor market: arguably the largest industry



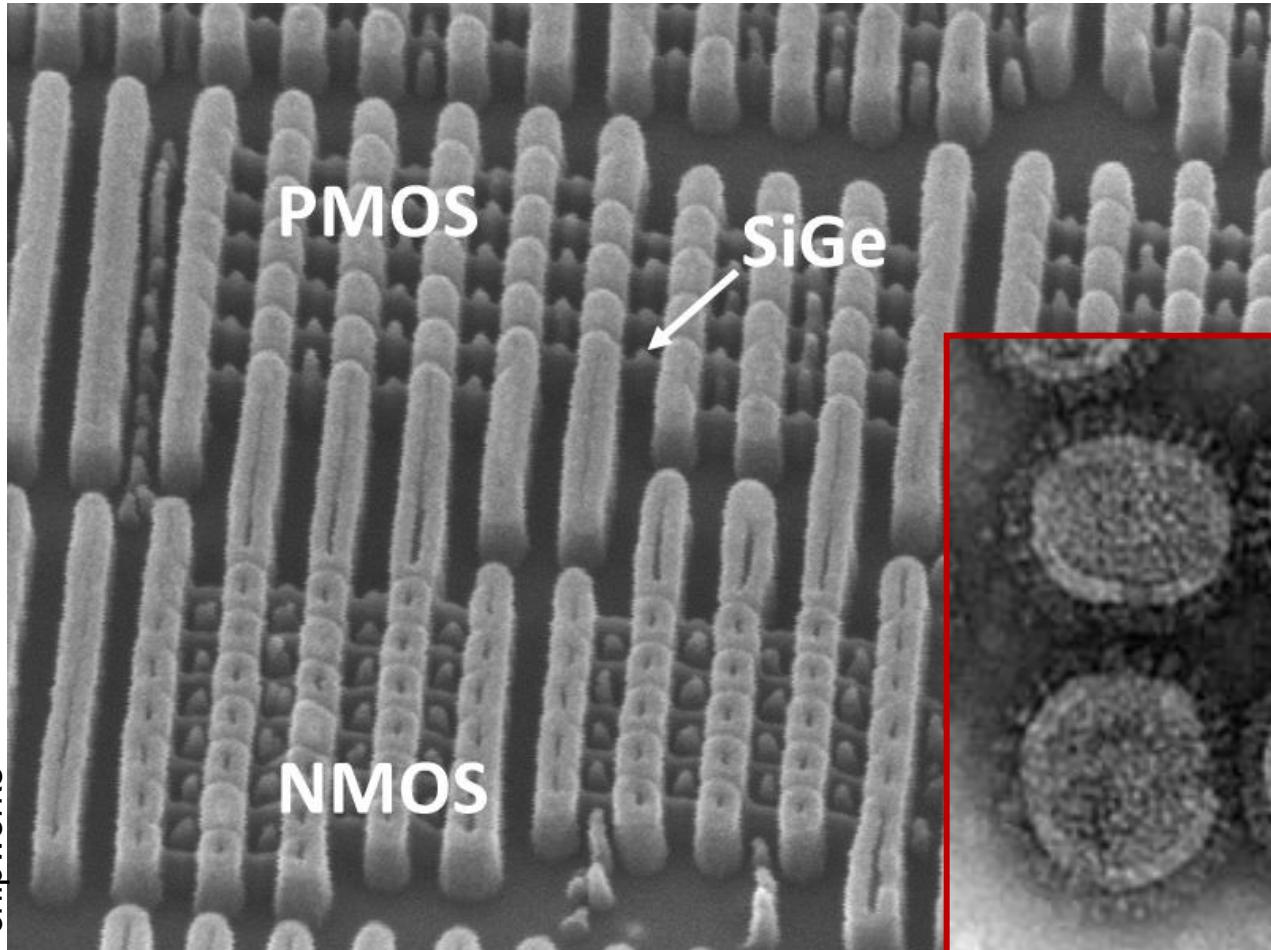
CPU clock frequency



Trends like Moore's “Law” are not forever



Inside a TriGate chip



iM C10
INTEL® XEON® E3-1230V2
SR0P4 3.30GHZ
MALAY
L201B603 (64)

H5N1 virus
(same scale)

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TIPP 2014, Amsterdam